



BOND FINGER CONFIGURATION

12. TIE BAR END CONFIGURATION IS VENDORS OPTION.
13. THIS DIMENSION IS THE MINIMUM CLEARANCE BETWEEN THE BRAZE PAD METALLIZATION AND THE TOP OF THE PACKAGE.
14. LEAD RESISTANCE SHALL BE 0.500 OHMS MAX.
15. WHEN TESTED IN ACCORDANCE WITH MIL STD 883, TEST METHOD 2001, CONDITION D, IN THE Y-1 DIRECTION, THE PACKAGE SHALL BE CAPABLE OF WITHSTANDING 20K G'S CONSTANT ACCELERATION.
16. A MINIMUM CLEARANCE OF .005 INCH SHALL BE MAINTAINED BETWEEN THE SEAL RING AND OTHER EXTERNAL METALLIZED FEATURES.
17. SIDE PLATING STRIP METALLIZATION DISCONNECTED BY GRINDING AFTER PLATING.